

## Thermosetting Adhesive / UV curing Adhesive

### 熱硬化接着剤/UV硬化接着剤



#### Applications 用途

Camera module, Image sensor, etc.  
カメラモジュール、イメージセンサなど



Corresponding to the diverse applications such as adhesion, filling sealing, dam formation.  
Rapid curing at low temperatures and excellent adhesion.(Epoxy resin)  
Designed for curing with low-energy irradiation including LED-based UV light sources.(UV curing resin)  
接着剤、充填封止、ダム形成など、多岐用途に対応。低温速硬化で優れた接着性を発揮。(エポキシ樹脂)  
低エネルギー照射での硬化を実現。(UV硬化樹脂)

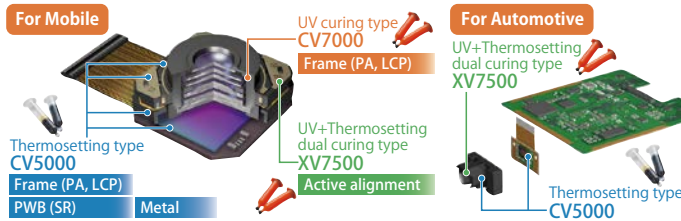
Bonding of various materials  
各種材質接着

Solvent resistance  
耐溶剤性

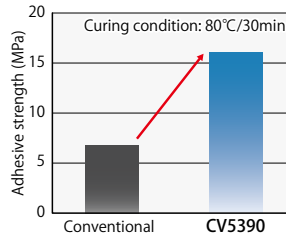
Time lagged curing  
時間差硬化

#### Use site and characteristics 使用部位と特性

Liquid adhesive with high adhesion, viscosity stability, workability and low-temperature rapid curability. Available for bonding of plastic lenses and housings in camera module and image sensor that requires positional accuracy and low temperature bonding.

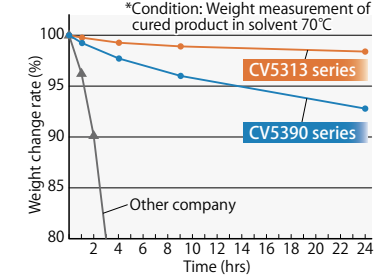


#### LCP adhesive strength



\*The data are indicated only for reference, and are not guaranteed.

#### Solvent resistance evaluation (Weight change)



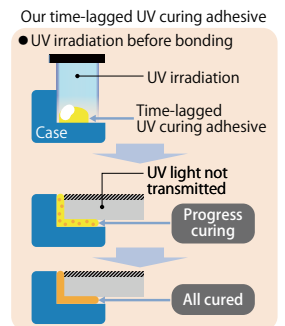
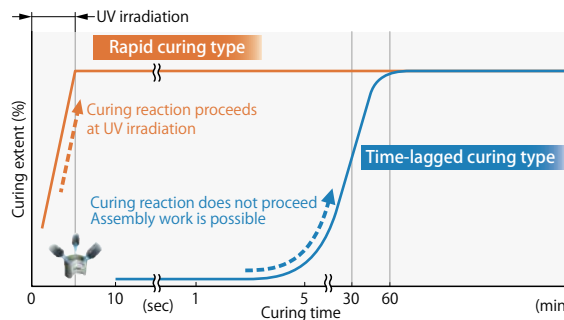
#### Features of UV time-lagged curing UV時間差硬化タイプ(XV7831)の特長

The time-lagged UV curing type can control the open time and curing time according to the application.

Since UV light is irradiated before bonding, it is possible to cure the dark area.

It can be cured at low temperature and in a short time, achieving temporary curing and lead time reduction.

High shape retention and high aspect ratio coating.



#### General properties 一般特性

Item	Unit	CV5390	XV7831
Type	—	Thermosetting	UV (Time-lagged) curing
Viscosity	Pa·s	3	45
Thixotropic index	—	1.0	1.1
Tg / C.T.E	°C / ppm/K	80 / 70	35 / 75
Pot life @25°C	days	3	2
Curing condition	—	80°C/10-30min	365nm LED-UV: 500mJ/cm <sup>2</sup> + Normal temp. leaving 4hrs or more*

\*Curing time can be shortened by heating +50°C 30min. +60°C 15min.

The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。